## Nch 650V 7A Power MOSFET

V <sub>DSS</sub>	650V
R <sub>DS(on)</sub> (Max.)	0.665Ω
I <sub>D</sub>	±7A
P <sub>D</sub>	46W

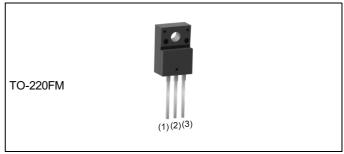
#### Features

- 1) Low on-resistance
- 2) Fast switching
- 3) Parallel use is easy
- 4) Pb-free plating; RoHS compliant

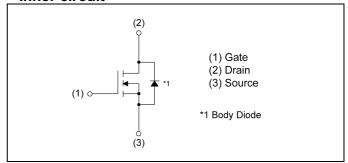
## Application

Switching

## Outline



## ●Inner circuit



Packaging specifications

Code	Packing	
C7 G	Tube	
C7	Tube*	
- (Blank)	Bulk*	

<sup>\*</sup>Package dimensions are different

## ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit	
Drain - Source voltage		$V_{DSS}$	650	V
Continuous drain current		I <sub>D</sub> *1	±7	А
Pulsed drain current	l <sub>DP</sub> *2	±21	А	
O-t- O	static	V <sub>GSS</sub>	±20	V
Gate - Source voltage	AC(f>1Hz)		±30	V
Avalanche current, single pulse	·	I <sub>AS</sub>	1.3	А
Avalanche energy, single pulse		E <sub>AS</sub> *3	136	mJ
Power dissipation (T <sub>c</sub> = 25°C)		$P_{D}$	46	W
Junction temperature		T <sub>j</sub>	150	°C
Operating junction and storage te	emperature range	T <sub>stg</sub>	-55 to +150	°C

## ●Thermal resistance

Downwortow	Cymah al	Values			1.1:4
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *4	-	-	2.7	°C/W
Thermal resistance, junction - ambient	R <sub>thJA</sub>	-	-	70	°C/W
Soldering temperature, wavesoldering for 10s	T <sub>sold</sub>	-	-	265	°C

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Davameter	Cymah al	Conditions	Values			Linit
Parameter	Parameter Symbol Conditions		Min.	Тур.	Max.	Unit
Drain - Source breakdown voltage	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		650	-	1	V
		V <sub>DS</sub> = 650V, V <sub>GS</sub> = 0V				
Zero gate voltage drain current	I <sub>DSS</sub>	$T_j = 25^{\circ}C$	-	-	100	μΑ
		$T_j = 125^{\circ}C$	ı	-	1000	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	1	-	±100	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 200 \mu A$	2	-	4	V
		$V_{GS} = 10V, I_D = 2.4A$				
Static drain - source on - state resistance	R <sub>DS(on)</sub> *5	$T_j = 25^{\circ}C$	-	0.605	0.665	Ω
		$T_j = 125^{\circ}C$	ı	1.20	ı	
Gate resistance	$R_{G}$	f = 1MHz, open drain	-	10.6	-	Ω

## ● Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Cymah al	Conditions	Values			Unit
Parameter	Symbol	ool Conditions		Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	390	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	500	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	60	-	
Turn - on delay time	t <sub>d(on)</sub> *5	$V_{DD} \simeq 300V$ , $V_{GS} = 10V$	-	18	-	
Rise time	t <sub>r</sub> *5	I <sub>D</sub> = 3.5A	-	25	-	
Turn - off delay time	t <sub>d(off)</sub> *5	$R_L \simeq 86.6\Omega$	-	65	-	ns
Fall time	<b>t</b> <sub>f</sub> *5	$R_G = 10\Omega$	-	40	-	

## ● Gate charge characteristics (T<sub>a</sub> = 25°C)

Darameter	Symbol Conditions -		Values			l limit
Parameter			Min.	Тур.	Max.	Unit
Total gate charge	$Q_g^{*5}$	V <sub>DD</sub> ≈ 300V	-	20	-	
Gate - Source charge	Q <sub>gs</sub> *5	I <sub>D</sub> = 7A	-	3	-	nC
Gate - Drain charge	Q <sub>gd</sub> *5	V <sub>GS</sub> = 10V	-	11	-	
Gate plateau voltage	V <sub>(plateau)</sub>	V <sub>DD</sub> ≈ 300V, I <sub>D</sub> = 7A	-	6.0	-	V

<sup>\*1</sup> Limited only by maximum channel temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L $\doteqdot$ 100mH, V<sub>DD</sub>=50V, R<sub>G</sub>=25 $\Omega$ , STARTING T<sub>j</sub>=25 $^{\circ}$ C

<sup>\*4</sup> T<sub>C</sub>=25°C

<sup>\*5</sup> Pulsed

## ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Parameter	Symbol	Conditions	Values			Unit
- Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Source current	I <sub>S</sub> *1	T - 25°C	-	-	7	Α
Pulsed source current	I <sub>SP</sub> *2	T <sub>C</sub> = 25°C	-	-	21	Α
Source-Drain voltage	V <sub>SD</sub> *5	$V_{GS} = 0V, I_{S} = 7A$	-	-	1.5	٧
Reverse recovery time	<b>t</b> <sub>rr</sub> *5		-	360	-	ns
Reverse recovery charge	Q <sub>rr</sub> *5	I <sub>S</sub> = 7A di/dt = 100A/μs	-	3.1	-	μC
Peak reverse recovery current	<sub>rr</sub> *5		-	17	-	А

Fig.1 Power Dissipation Derating Curve

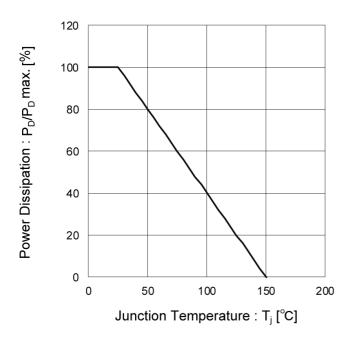


Fig.2 Drain Current Derating Curve vs. Junction Temperature

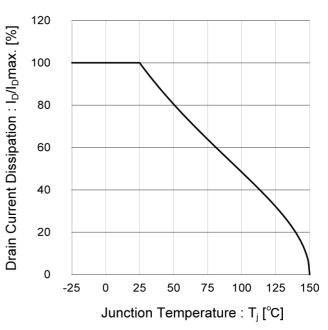


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

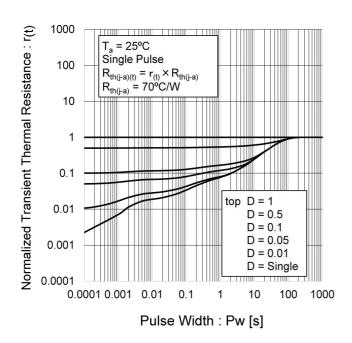


Fig.4 Maximum Safe Operating Area

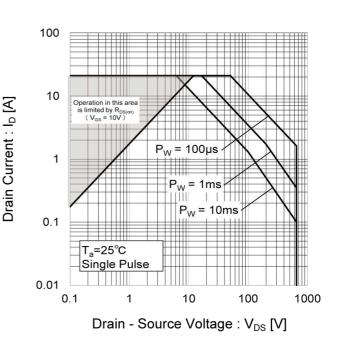


Fig.5 Avalanche Energy Derating Curve vs. Junction Temperature

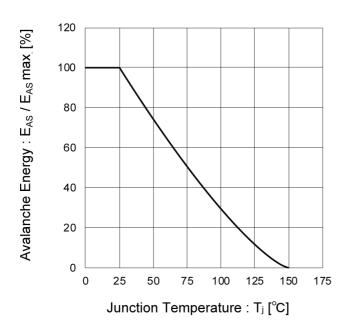


Fig.6 Normalized Breakdown Voltage vs. Junction Temperature

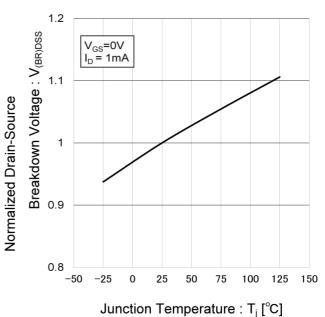
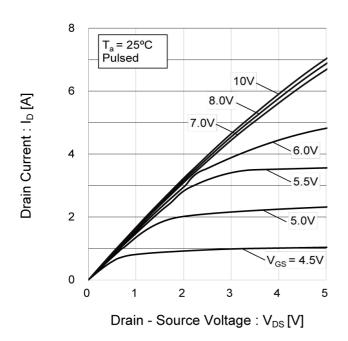


Fig.7 Typical Output Characteristics(I)



Drain Current : I<sub>D</sub> [A]

8 10V T<sub>a</sub> = 25°C Pulsed 8.0V 7.0V 6.0V 6 5.5V 4 5.0V 2  $V_{GS} = 4.5V$ 0 10 0 20 30 50 Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.8 Typical Output Characteristics(II)

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Fig.9 Typical Transfer Characteristics

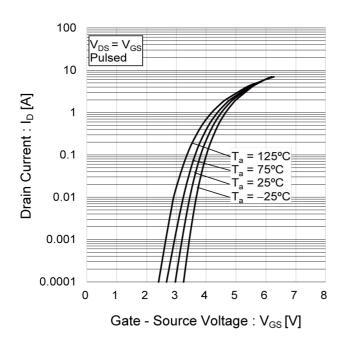


Fig.10 Normalized Gate Threshold

Voltage vs. Junction Temperature

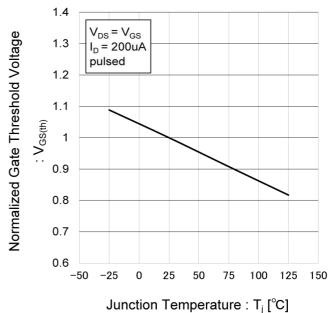


Fig.11 Static Drain - Source On - State Resistance vs. Drain Current

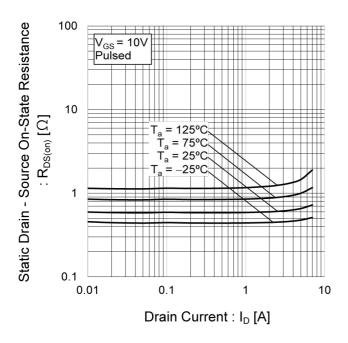


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

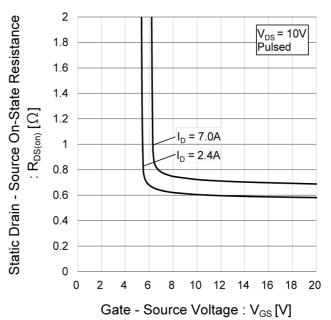


Fig.13 Normalized Static Drain - Source On - State Resistance vs. Junction Temperature

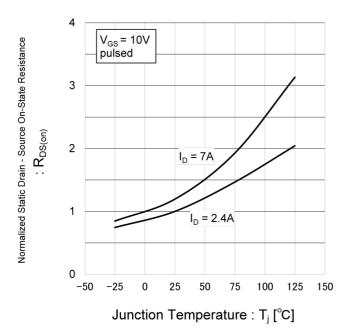
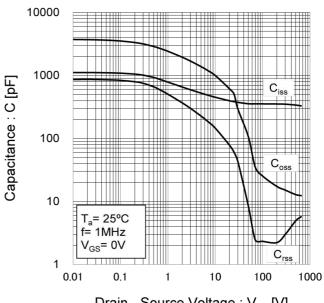


Fig.14 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.15 Switching Characteristics

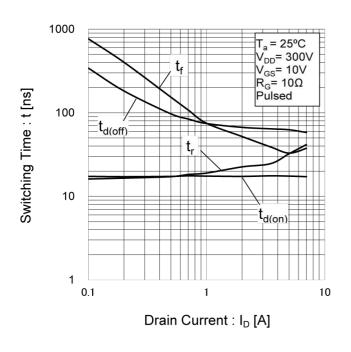
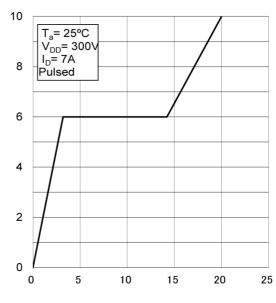


Fig.16 Typical Gate Charge



Total Gate Charge : Q<sub>g</sub> [nC]

Gate - Source Voltage : V<sub>GS</sub> [V]

Fig.17 Source Current vs. Source - Drain Voltage

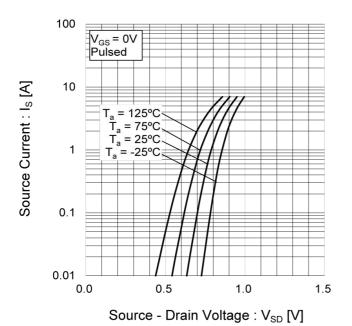
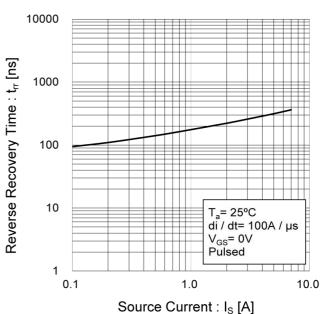


Fig.18 Reverse Recovery Time vs. Source Current



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#### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

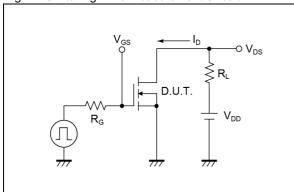


Fig.2-1 Gate Charge Measurement Circuit

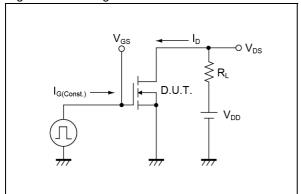


Fig.3-1 Avalanche Measurement Circuit

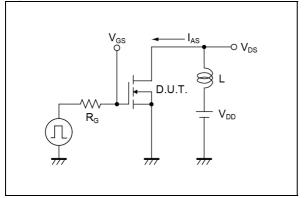


Fig.4-1 trr Measurement Circuit

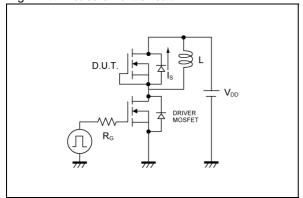


Fig.1-2 Switching Waveforms

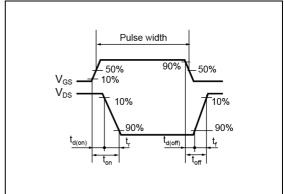


Fig.2-2 Gate Charge Waveform

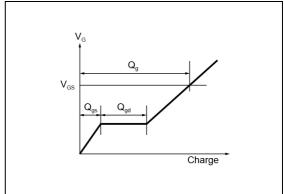


Fig.3-2 Avalanche Waveform

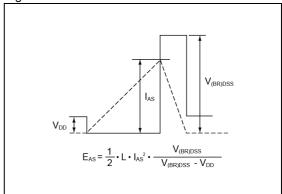
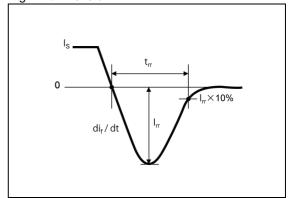
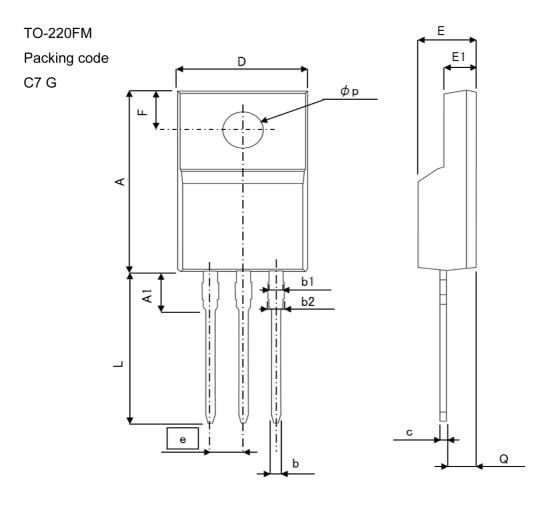


Fig.4-2 trr Waveform



## Dimensions

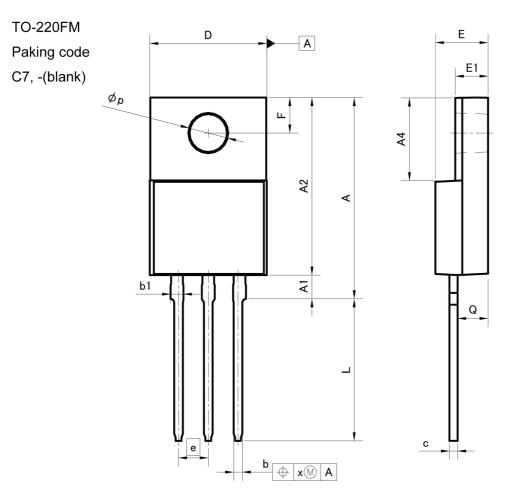


DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	15.67	16.27	0.617	0.641
A1	3.03	3.43	0.119	0.135
b	0.70	0.95	0.028	0.037
b1	1.00	1.40	0.039	0.055
b2	1.10	1.50	0.043	0.059
С	0.45	0.65	0.018	0.026
D	9.90	10.30	0.390	0.406
E	4.60	5.00	0.181	0.197
E1	2.44	2.74	0.096	0.108
е	2.	54	0.100	
F	3.10	3.50	0.122	0.138
L	12.6	13.6	0.946	0.535
р	2.98	3.38	0.117	0.133
Q	2.25	3.25	0.089	0.128

Dimension in mm/inches



## Dimensions



DIM	MILIMI	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	16.60	17.60	0.654	0.693
A1	1.80	2.20	0.071	0.087
A2	14.80	15.40	0.583	0.606
A4	6.80	7.20	0.268	0.283
b	0.70	0.90	0.028	0.035
b1	1.10	1.50	0.043	0.059
С	0.70	0.85	0.028	0.033
D	9.90	10.30	0.390	0.406
E	4.40	4.80	0.173	0.189
е	2.	2.54		00
E1	2.70	3.00	0.106	0.118
F	2.80	3.20	0.110	0.126
L	11.50	12.50	0.453	0.492
р	3.00	3.40	0.118	0.134
Q	2.10	3.10	0.083	0.122
Х	_	0.38	_	0.015

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSIII
CLASSIV	CLASSIII	CLASSⅢ	CLASSIII

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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### **Precaution for Mounting / Circuit board design**

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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